

## Method of Managing Wafer Defects

Appl. No. : 10/711,310 Confirmation No.: 5309  
Applicants : Hung-En Tai,  
Chia-Yun Chen,  
Sheng-Jen Wang  
Filed : September 9, 2004  
TC/A.U. : 2624  
Examiner : CHAWAN, SHEELA C  
Docket No. : LKSP0051USA  
Customer No. : 27765

Commissioner for Patents  
P.O. Box 1450  
Alexandria VA 22313-1450

### AMENDMENT

Sir:

- 5 In response to the Office action of October 19, 2007, please amend the above-identified application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 4 of this paper.

- 10 **Remarks/Arguments** begin on page 7 of this paper.